

Notice of References Cited		Application/Control No.	Applicant(s)/Patent Under Reexamination	
		10/566,571	SAWAI, MASAYOSHI	
Examiner		Art Unit		Page 1 of 1
Tung S. Lau		2863		

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-			
	B	US-			
	C	US-			
	D	US-			
	E	US-			
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	D.S. Liu, Study of wire bonding looping formation in the electronic packaging process using three-dimensional finite element method, October 22, 2002, page 263-286
	V	http://mw1.merriam-webster.com/dictionary/tangent , page 1
	W	
	X	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.